

Summary

A method for producing a component (5) is provided, in particular a deformation sensor, having a sensor element (15) which includes at least one region (12) that is sensitive with respect to expansion or compression, as well as electrical structures (13, 14, 72) which are in connection therewith. To this end, a sacrificial layer (20) is produced on or within a substrate (21) and an activatable layer (10) on top of the sacrificial layer (20), the sensitive region (12) and at least a portion of the electrical structures (13, 14, 72) being positioned on top or within an activatable layer (10), and a circumferential trench (11) is produced around the region of the sensor element (15) to be produced and having the sensitive region (12) and the portion of the electrical structures (13, 14, 72), the trench being interrupted by at least one connecting point (25), which connects the region of the sensor element (15) to the portion of the activatable layer (10) lying outside the circumferential trench (11). This is followed by a removal of the sacrificial layer (20) underneath the region of the sensor element (15), a fixation of the region of the sensor element (15) with the aid of a holding device (50), rupturing of the connecting points (25) and a transfer of the sensor element (15), fixated by the holding device (50), and connecting a carrier (70) to the component (5) as well as joining with a carrier (70) to the component (5).

(Figure 2)